



SOT2088-1(SC)

HWQFN, plastic thermal enhanced very thin quad flat package; no leads, wettable flanks, 40 terminals, 0.4 mm pitch, 5.0 mm x 5.0 mm x 0.68 mm body

15 December 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN40
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Manufacturer package code	98ASA01692D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
seated height	0.65	0.68	0.75	mm
nominal pitch	-	0.4	-	mm



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2 Package outline

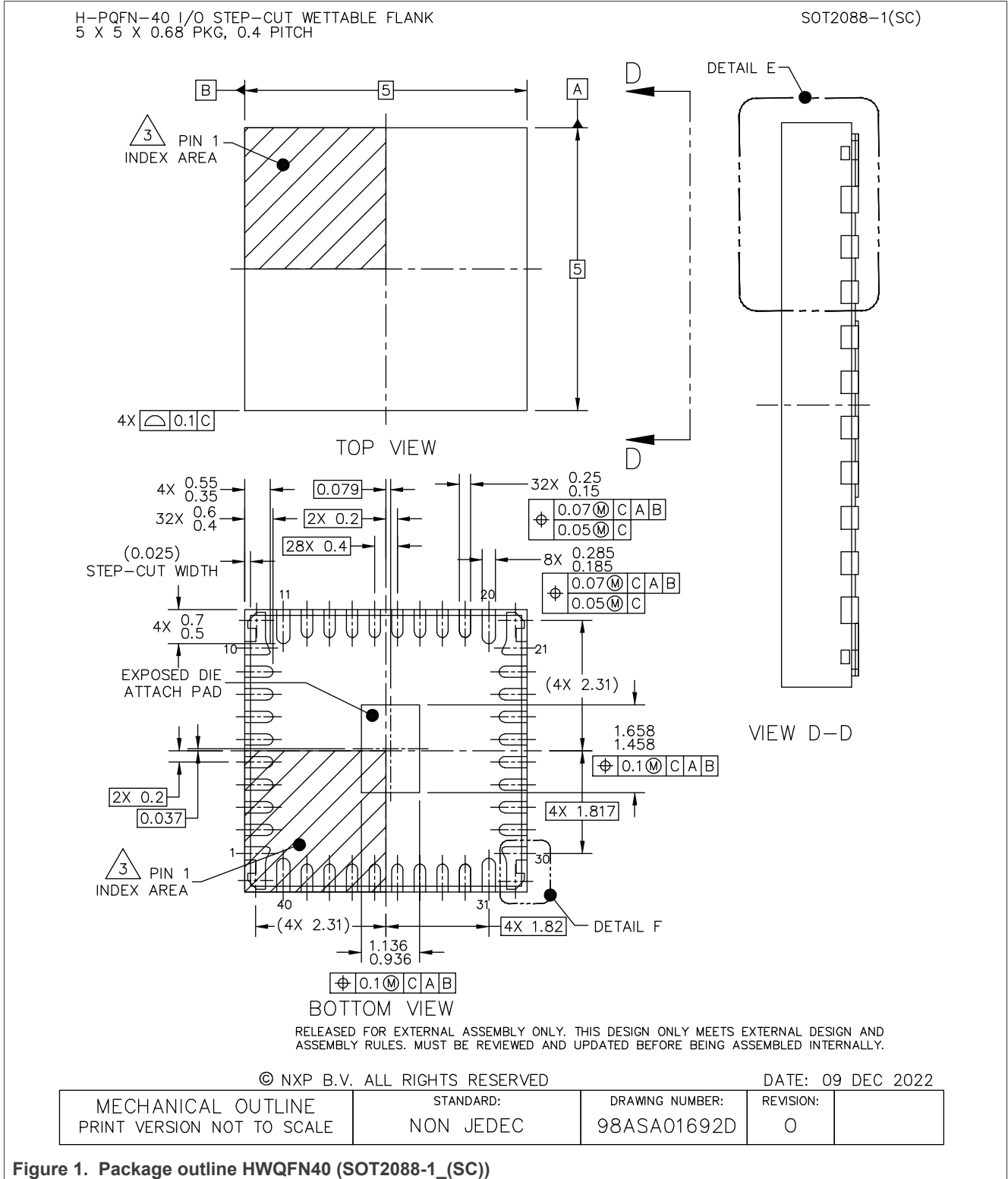


Figure 1. Package outline HWQFN40 (SOT2088-1(SC))

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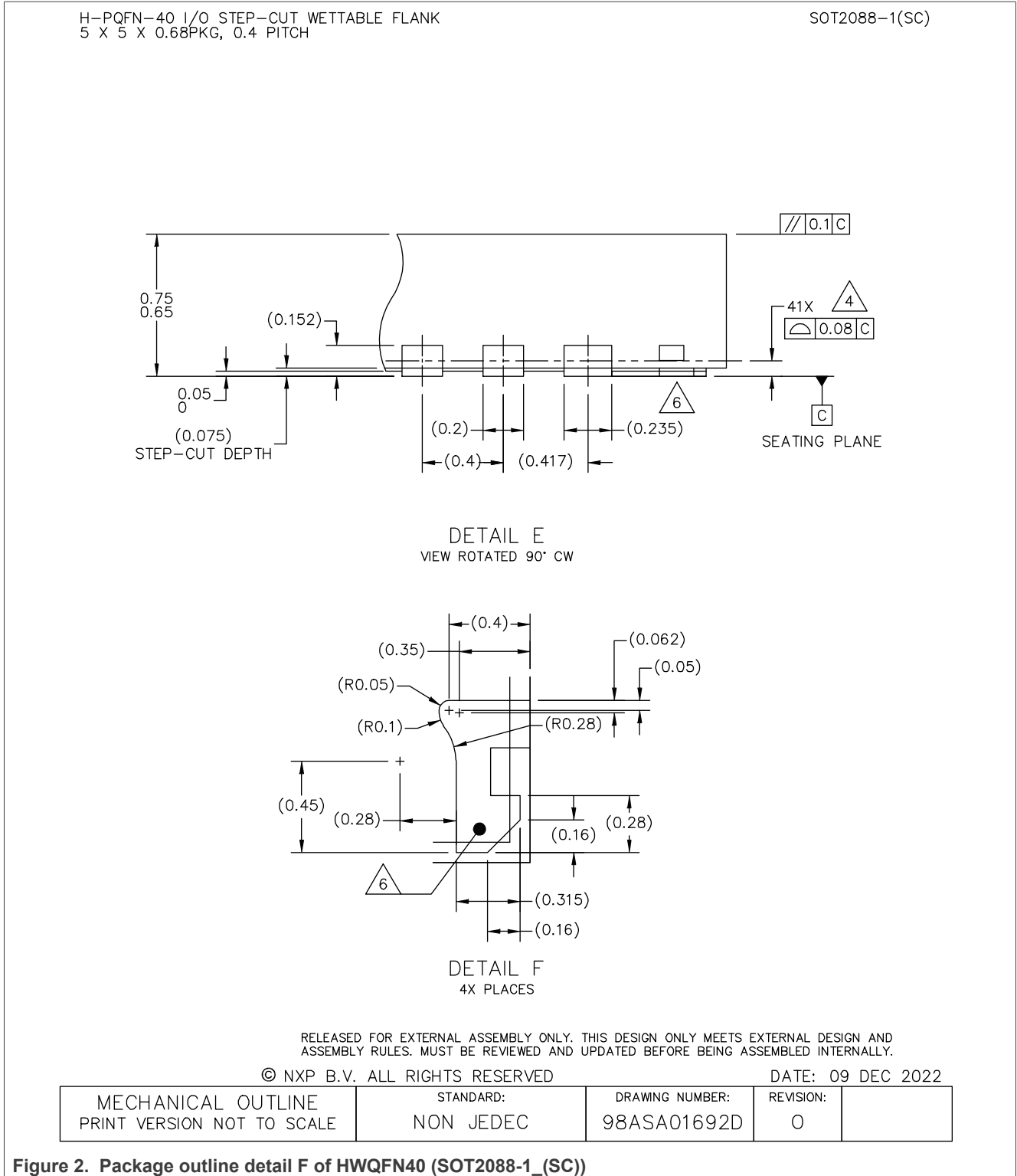


Figure 2. Package outline detail F of HWQFN40 (SOT2088-1(SC))

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3 Soldering

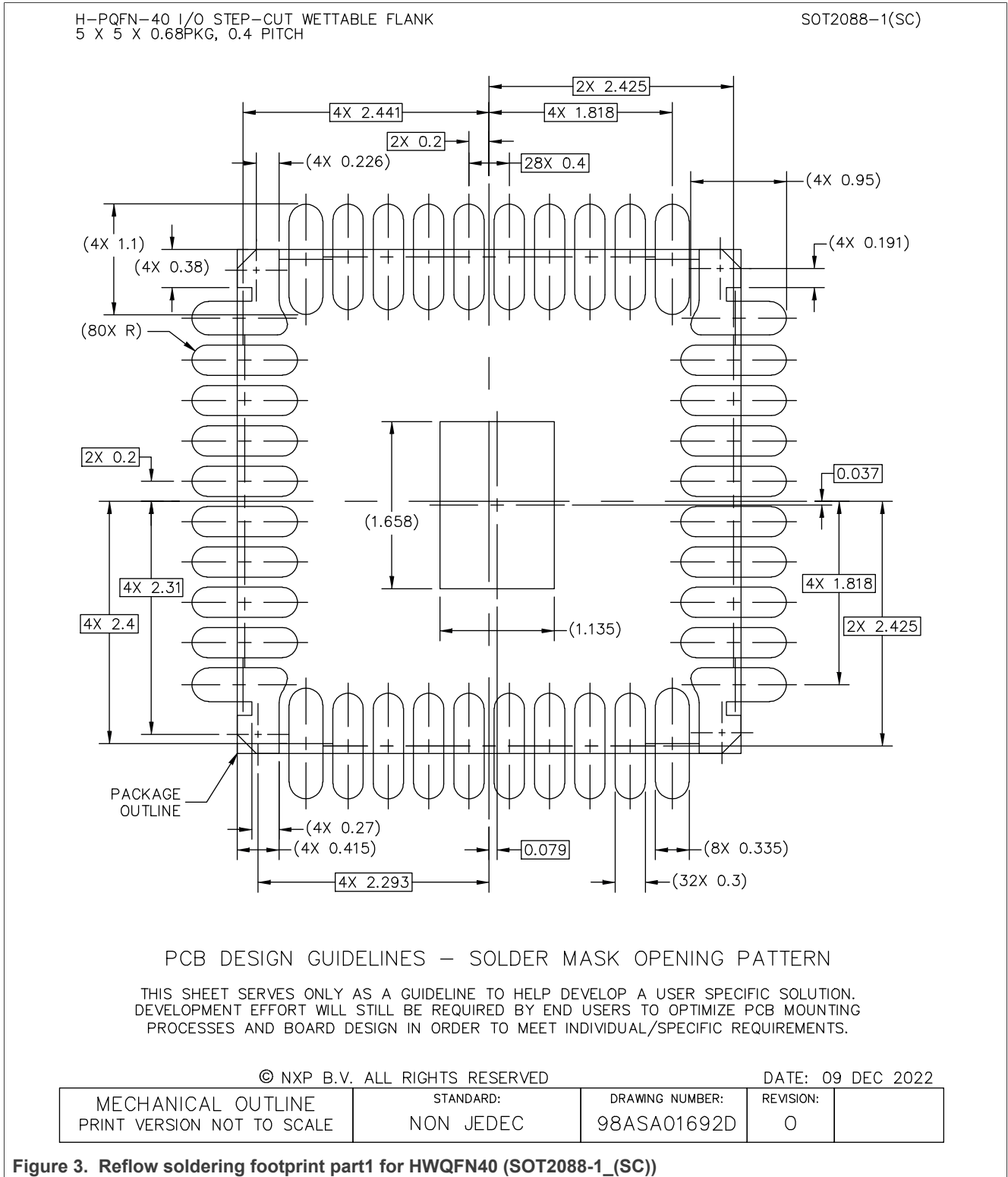
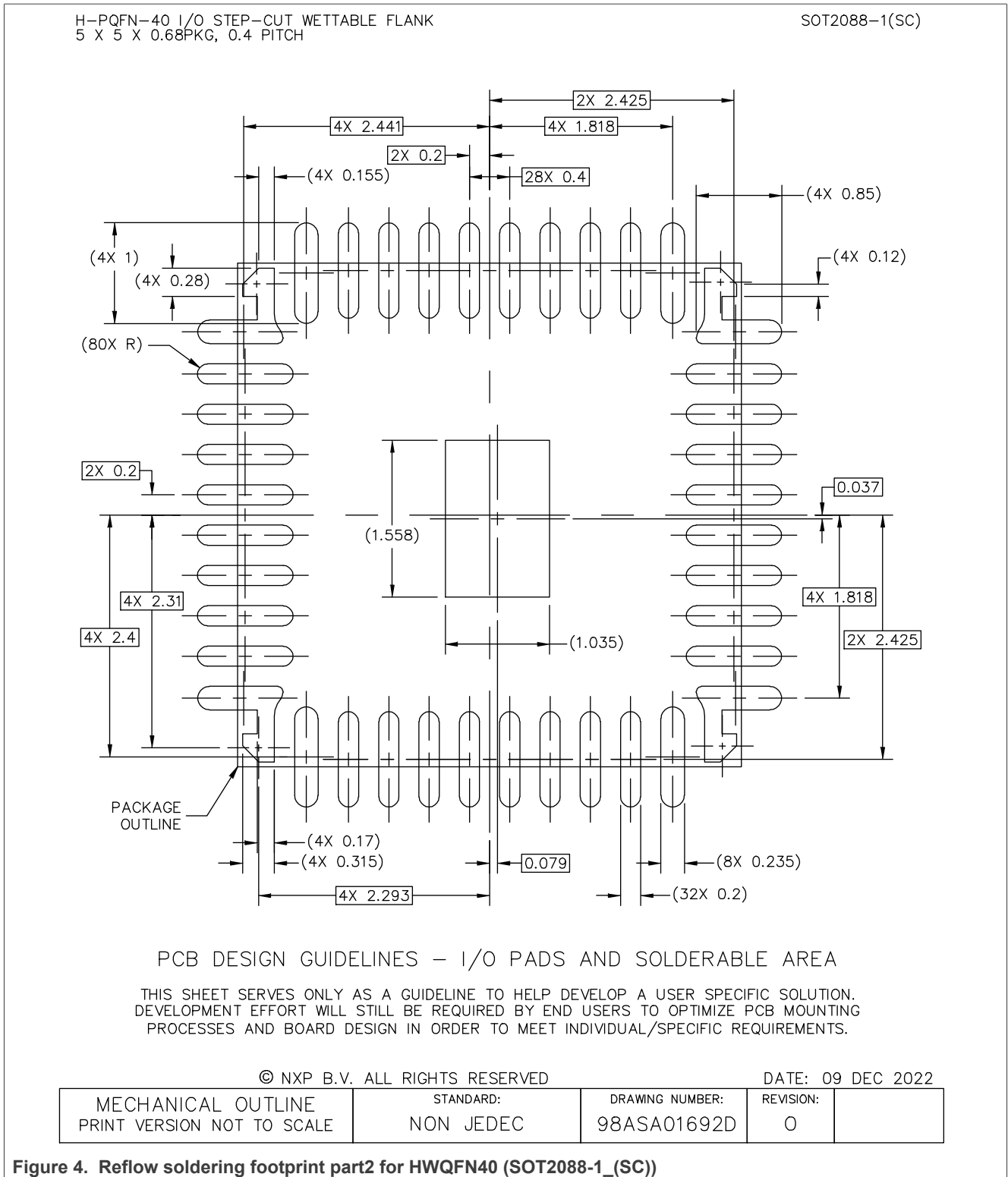


Figure 3. Reflow soldering footprint part1 for HWQFN40 (SOT2088-1(SC))

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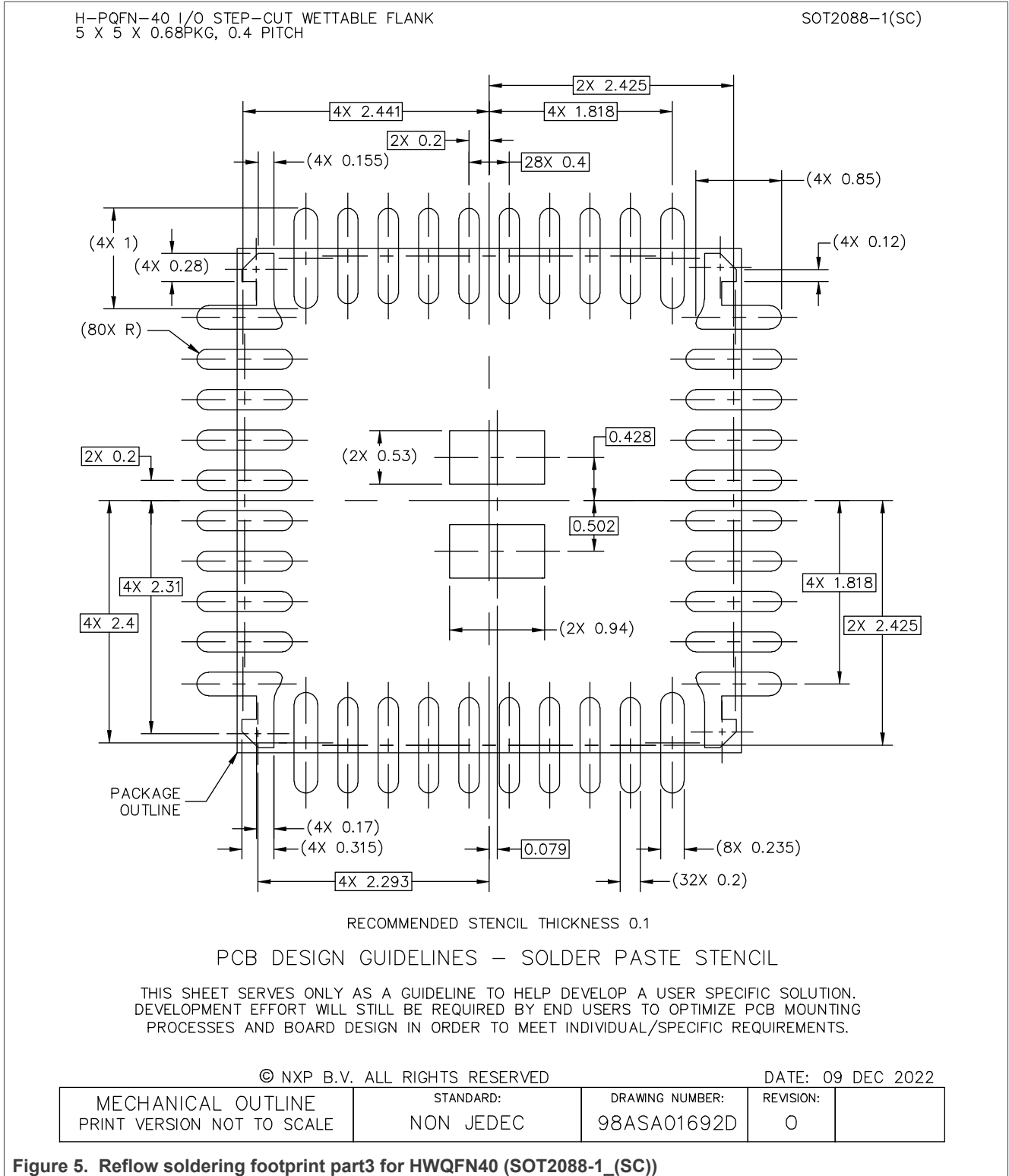


Figure 5. Reflow soldering footprint part3 for HWQFN40 (SOT2088-1(SC))

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H-PQFN-40 1/0 STEP-CUT WETTABLE FLANK
5 X 5 X 0.68PKG, 0.4 PITCH

SOT2088-1(SC)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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DATE: 09 DEC 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01692D	REVISION: 0	
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Figure 6. Package outline note HWQFN40 (SOT2088-1_(SC))

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4 Legal information

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